

Electronic Patent Application Fee Transmittal

Application Number:	10596387
Filing Date:	13-Apr-2007
Title of Invention:	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT
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Filer:	Joerg-Uwe V. Szipl/Janice Rosier
Attorney Docket Number:	MIYOSH0006

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180